

02-13-2001

t No.: BUR920000107US1(13790)

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Patent and Trademark Office

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1-30-01

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copies.

1. Name of conveying party(ies):

1. Jack Oon Chu, 2. Douglas Duane Coolbaugh,
3. James Stuart Dunn, 4. David R. Greenberg,
5. David L. Harame, 6. Basanth Jagannathan,
7. Robb Allen Johnson, 8. Louis D. Lanzerotti,

Additional names(s) of conveying party(ies) attached? ☒ Yes ☐ No

2. Name and address of receiving party(ies):

Name: International Business MachinesAddress: New Orchard RoadCity: ArmonkState/Prov.: New YorkCountry: U.S.A.ZIP: 10504

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

1/29/01, 12/18/00, 12/21/00, 12/20/00,
Execution Date: 1/25/01, 12/20/00, 1/16/01, 1/29/01,
12/20/00, 12/21/00

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or registration numbers(s):

09/174126

If this document is being filed together with a new application, the execution date of the application is: 1/29/01, 12/18/00, 12/21/00,
12/20/00, 1/25/01,
12/20/00, 1/16/01, 1/29/01, 12/20/00,
B. Patent No.(s) 12/21/00

Patent Application No.

Filing date

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Richard L. CataniaRegistration No. Registration No. 32,608Address: Scully, Scott, Murphy & Presser400 Garden City Plaza(516)742-4343City: Garden City State/Prov.: New YorkCountry: U.S.A. ZIP: 11530

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00☐ Enclosed - Any excess or insufficiency should be credited or debited to deposit account☒ Authorized to be charged to deposit account

8. Deposit account number:

09-0456/IBM

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

William D. Sabo, Reg. No. 27,465

Name of Person Signing

Signature

1/30/01

Date

Total number of pages including cover sheet, attachments, and document:

8

PATENT
REEL: 011510 FRAME: 0647

RECORDATION FORM COVER SHEET (Continued)

Docket No.: BUR920000107US1(13790)

1. Name of conveying party(ies):
 9. Katheryn Turner Schonenberg
 10. Ryan Wayne Wuthrich

Express Mail EK602286510US

(IBM Docket No.: BUR920000107US1)
(SSM&P Docket No. 13790)**ASSIGNMENT****Whereas, we**

Inventor and City	(1) Jack Oon Chu County of Nassau	City of Manhasset Hills and State of New York
and	(2) Douglas Duane Coolbaugh County of Chittenden	City of Essex Junction and State of Vermont
and	(3) James Stuart Dunn County of Chittenden	City of Jericho and State of Vermont
and	(4) David R. Greenberg County of Westchester	City of White Plains and State of New York
and	(5) David L. Haramé County of Chittenden	City of Essex Junction and State of Vermont
and	(6) Basanth Jagannathan County of Dutchess	City of Fishkill City of Stormville B.S. and State of New York
and	(7) Robb Allen Johnson County Chittenden	City of South Burlington and State of Vermont
and	(8) Louis D. Lanzerotti County of Chittenden	City of Burlington and State of Vermont
and	(9) Katheryn Turner Schonenberg County of Fairfield	City of New Fairfield and State of Connecticut
and	(10) Ryan Wayne Wuthrich County of Chittenden	City of Burlington and State of Vermont

have invented certain improvements in

Title INCORPORATION OF CARBON IN SILICON/SILICON GERMANIUM EPITAXIAL
LAYER TO ENHANCE YIELD FOR Si-Ge BIPOLAR TECHNOLOGY

Dates That Inventors Signed the Declaration and have executed, respectively, a United States patent application therefor on

(1) 1/29	²⁰⁰¹ 2000, and (2) 12/18	2000, and
(3) 12/21	2000, and (4) 12/20	2000, and
(5) 01/25	2000, and (6) 12/20	2000, and
(7) 1/10/2001	2000 , and (8) 2/24/01	2000 , and
(9) 12/20	2000, and (10) 12/21/00	2000.

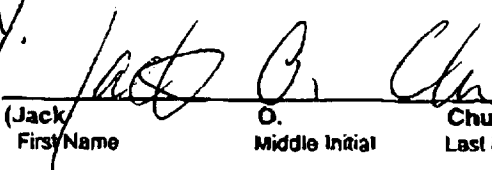
Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

(IBM Docket No.: BUR920000107US1)
(SSM&P Docket No. 13790)

ASSIGNMENT (Continued)

TITLE: INCORPORATION OF CARBON IN SILICON/SILICON GERMANIUM EPITAXIAL
LAYER TO ENHANCE YIELD FOR Si-Ge BIPOLAR TECHNOLOGY

City	(1) Signed at	Yorktown, N.Y.				signature
Date	on	1-29-2001	(Jack	O.	Chu) inventor
			First Name	Middle Initial	Last Name	
City	(2) Signed at					signature
Date	on		(Douglas	D.	Cholbaugh) inventor
			First Name	Middle Initial	Last Name	
City	(3) Signed at					signature
Date	on		(James	S.	Dunn) inventor
			First Name	Middle Initial	Last Name	
City	(4) Signed at					signature
Date	on		(David	R.	Greenberg) inventor
			First Name	Middle Initial	Last Name	
City	(5) Signed at					signature
Date	on		(David	L.	Haramo) inventor
			First Name	Middle Initial	Last Name	
City	(6) Signed at					signature
Date	on		(Basant		Jagannathan) inventor
			First Name	Middle Initial	Last Name	
City	(7) Signed at					signature
Date	on		(Robb	A.	Johnson) inventor
			First Name	Middle Initial	Last Name	
City	(8) Signed at					signature
Date	on		(Louis	D.	Lanzerotti) inventor
			First Name	Middle Initial	Last Name	

(IBM Docket No.: BUR920000107US1)
(SSM&P Docket No. 13790)

ASSIGNMENT (Continued)

TITLE: INCORPORATION OF CARBON IN SILICON/SILICON GERMANIUM EPITAXIAL
LAYER TO ENHANCE YIELD FOR Si-Ge BIPOLAR TECHNOLOGY

City (1) Signed at

Date on

(Jack O. Chu) signature
First Name Middle Initial Last Name) inventor

City (2) Signed at *Essex Junction*

Date on *12/18/00*

(Douglas D. Coolbaugh) signature
First Name Middle Initial Last Name) inventor

City (3) Signed at *ESSEX JUNCTION*

Date on *12/21/00*

(James S. Dunn) signature
First Name Middle Initial Last Name) inventor

City (4) Signed at

Date on

(David R. Greenberg) signature
First Name Middle Initial Last Name) inventor

City (5) Signed at *ESSEX JUNCTION VERMONT*

Date on *January 25, 2001*

(David L. Harnes) signature
First Name Middle Initial Last Name) inventor

City (6) Signed at

Date on

(Basant Jagannathan) signature
First Name Middle Initial Last Name) inventor

City (7) Signed at *ESSEX JUNCTION, VT*

Date on *1/16/2001*

(Robb A. Johnson) signature
First Name Middle Initial Last Name) inventor

City (8) Signed at *Essex Junction VT*

Date on *1/29/01*

(Louis D. Lanzerotti) signature
First Name Middle Initial Last Name) inventor

(IBM Docket No.: BUR920000107US1)
(SSM&P Docket No. 13790)

ASSIGNMENT (Continued)

TITLE: INCORPORATION OF CARBON IN SILICON/SILICON GERMANIUM EPITAXIAL
LAYER TO ENHANCE YIELD FOR Si-Ge BIPOLAR TECHNOLOGY

City (1) Signed at

Date on

(Jack O. Chu) signature
First Name Middle Initial Last Name) Inventor

City (2) Signed at Essex Junction

Date on 12/18/00

(Douglas D. Coolbaugh) signature
First Name Middle Initial Last Name) Inventor

City (3) Signed at

Date on

(James S. Dunn) signature
First Name Middle Initial Last Name) Inventor

City (4) Signed at East Fishkill

Date on 12/20/2000

(David R. Greenberg) signature
First Name Middle Initial Last Name) Inventor

City (5) Signed at

Date on

(David L. Harnes) signature
First Name Middle Initial Last Name) Inventor

City (6) Signed at East Fishkill

Date on 12/20/2000

(Basant Jagannathan) signature
First Name Middle Initial Last Name) Inventor

City (7) Signed at

Date on

(Robb A. Johnson) signature
First Name Middle Initial Last Name) Inventor

City (8) Signed at

Date on

(Louis D. Lanzerotti) signature
First Name Middle Initial Last Name) Inventor

(IBM Docket No.: BUR920000107US1)
(SSM&P Docket No. 13790)

ASSIGNMENT (Continued)

TITLE: INCORPORATION OF CARBON IN SILICON/SILICON GERMANIUM EPITAXIAL
LAYER TO ENHANCE YIELD FOR Si-Ge BIPOLAR TECHNOLOGY

City (9) Signed at East Fishkill

Date on 12/20/2000

 signature
(Kathryn T. Schonenberg) inventor
First Name Middle Initial Last Name

City (10) Signed at

Date on

 signature
(Ryan W. Wuthrich) inventor
First Name Middle Initial Last Name

ASSIGNMENT (Continued)

TITLE: INCORPORATION OF CARBON IN SILICON/SILICON GERMANIUM EPITAXIAL
LAYER TO ENHANCE YIELD FOR Si-Ge BIPOLAR TECHNOLOGY

City (9) Signed at

Date on

(Katheryn	T.	Schonenberg)	signature
First Name	Middle Initial	Last Name	inventor

City (10) Signed at ESSEX JUNCTION, VT ~~ESSEX~~

Date on 12/21/00

(Ryan	W.	Wuthrich	signature
First Name	Middle Initial	Last Name) inventor